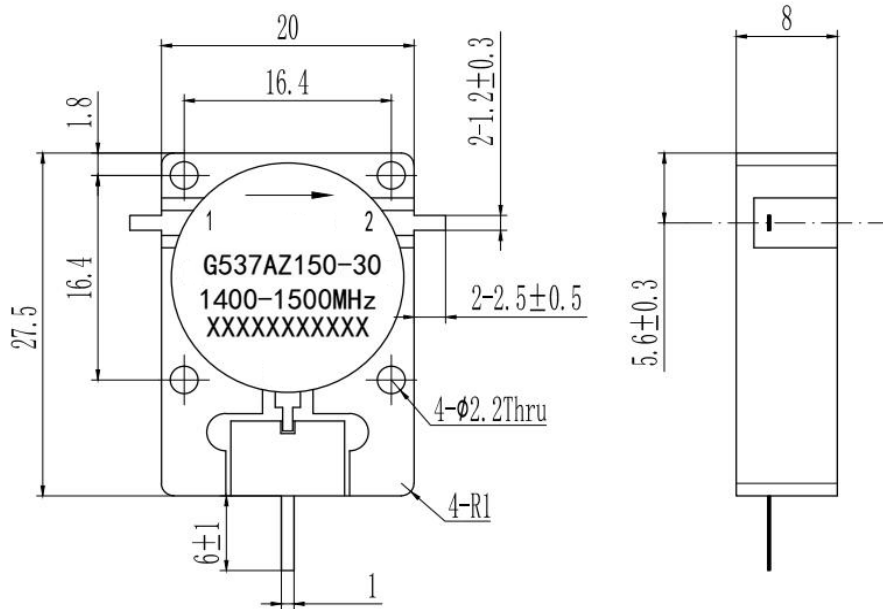


### 1.Features

- UMTS, LTE Band
- PCB Soldering Re-flow
- Wide Operation Temperature Range -40 ~ 85°C
- Compact Package Design for PCB Applications

### 2.Dimensions



### 3.Specifications

Part No.	Frequency (GHz)		Center Frequency	Bandwidth	Isolation	INS LOSS	VSWR	Power	IMD (@2X43dBm)
	F1	F2	(GHz)	(GHz)	(dB) MIN	(dB) MAX	(dB) MAX	(W)	(-dBc) MAX
G537A[851-866]MHz	0.851	0.866	0.859	0.015	25	0.25	1.15	150	
G537A[865-880]MHz	0.865	0.880	0.873	0.015	23	0.3	1.15	150	
G537A[869-894]MHz	0.869	0.894	0.8815	0.025	23	0.3	1.15	150	
G537A[880-920]MHz	0.880	0.920	0.9000	0.040	23	0.3	1.15	150	
G537A[920-960]MHz	0.920	0.960	0.9400	0.040	23	0.3	1.15	100	
G537A[1452-1492]MHz	1.452	1.492	1.4720	0.040	25	0.25	1.15	100	
G537A[1710-1755]MHz	1.710	1.755	1.7325	0.045	25	0.25	1.15	150	
G537A[1805-1880]MHz	1.805	1.880	1.8375	0.075	23	0.25	1.15	100	
G537A[1805-1920]MHz	1.805	1.920	1.8625	0.115	22	0.25	1.17	100	
G537A[1920-1980]MHz	1.920	1.980	1.9500	0.060	23	0.25	1.15	150	
G537A[2010-2025]MHz	2.010	2.025	2.0175	0.015	23	0.25	1.15	100	
G537A[2110-2170]MHz	2.110	2.170	2.1400	0.060	23	0.25	1.15	150	
G537A[2400-2500]MHz	2.400	2.500	2.4500	0.100	23	0.25	1.15	100	
G537A[2620-2690]MHz	2.620	2.690	2.6550	0.070	23	0.25	1.15	150	